

# Solder Reflow Profiles for HSS™ ICs

## Overview

Figure 1 shows *AlSentis*' recommended profiles for Pb-free devices. These devices are plated with matte Tin (Pure Sn) and contain no lead. They can be used in standard tin-lead (SnPb) applications, using a profile that is equal to or above the lower line in the plot, or in Pb-free solder such as Tin-Silver-Copper (Sn-Ag-Cu) with profiles up to and including the upper line on the plot.

Figure 2 shows *AlSentis*' recommended profiles for standard devices with 63%/37% tin-lead (Sn-Pb) solder finish. The reflow profile for these devices can be anywhere between the upper and lower curves shown in Figure 2. Please note that the peak temperature is lower than that of the Pb-free devices.

## Pb-Free Reflow Profile Recommendation

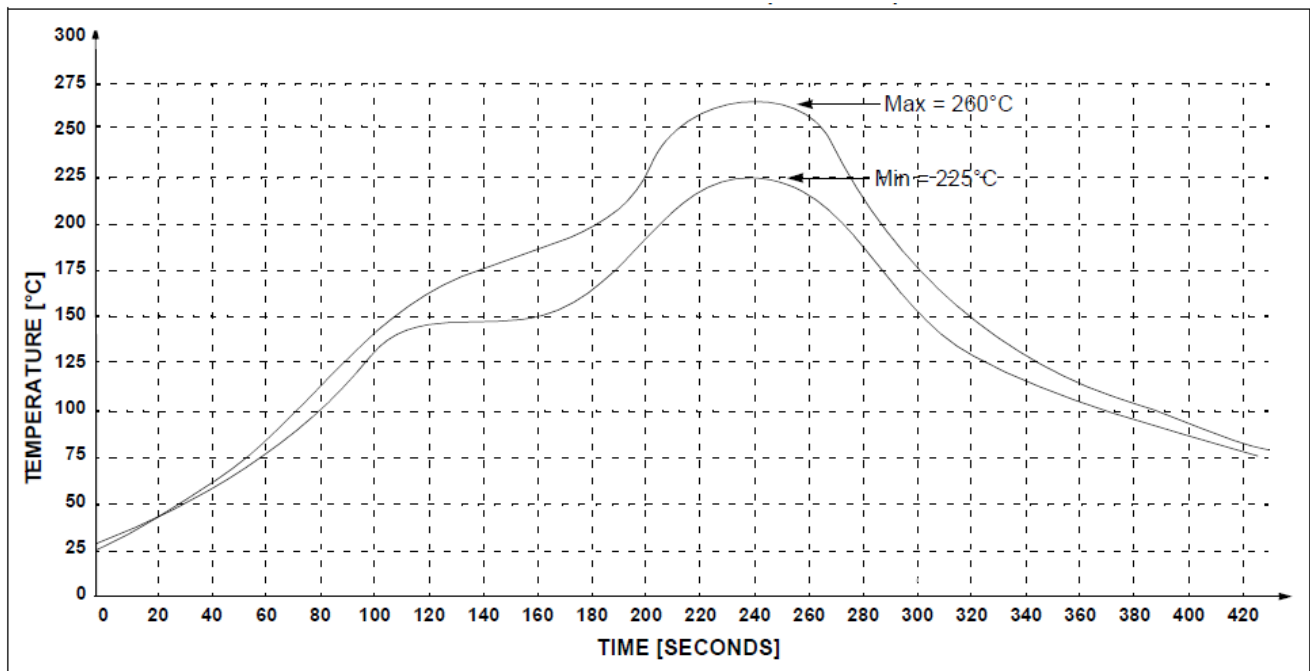


Figure 1

### Sn/Pb Reflow Profile Recommendation

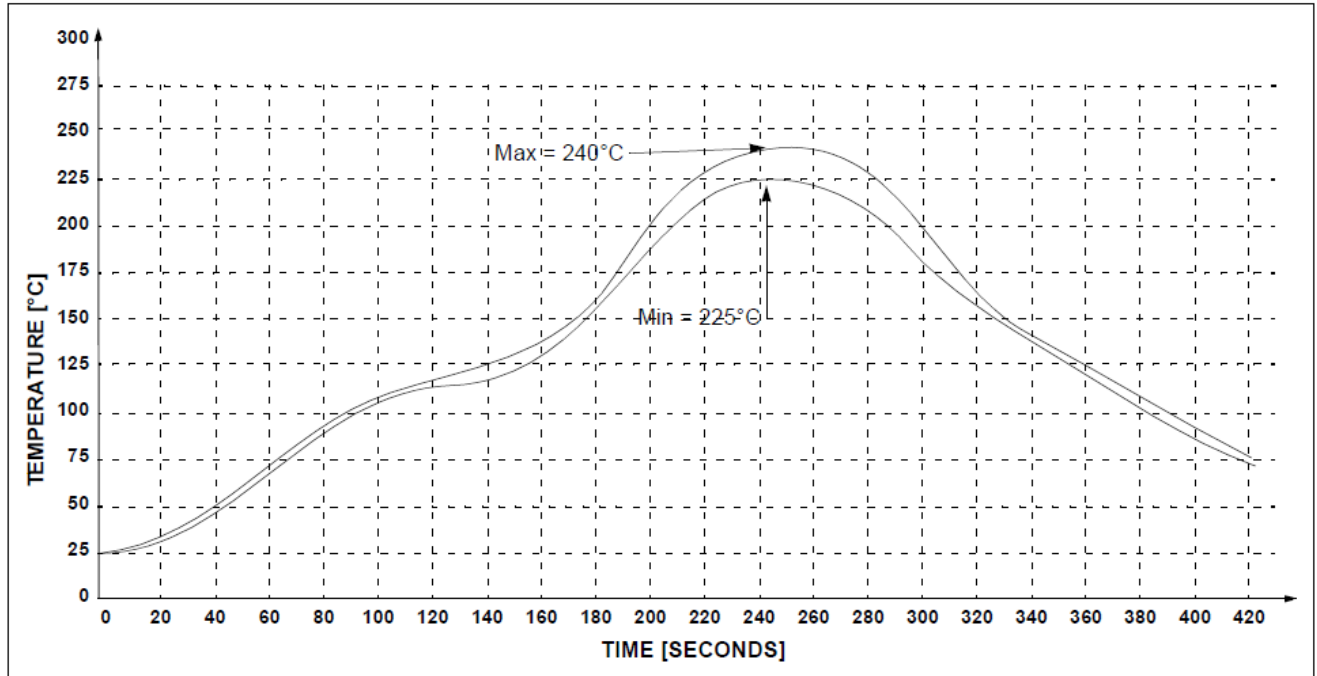


Figure 2